

# 650V Enhancement mode GaN HEMT

GNP3028TF-Z



## Features

- 650V E-mode GaN HEMT
- 28mΩ Resistance
- 10nC Gate Charge

## Package Information

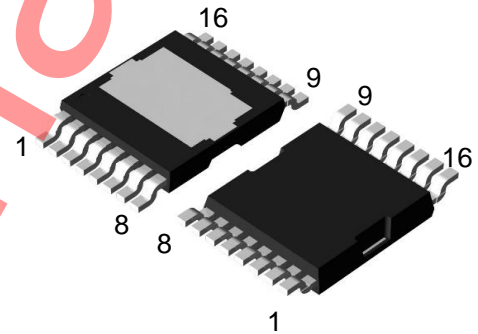
W (Typ) × D (Typ) × H (Max)

11.68 mm × 9.9 mm × 2.4 mm

TOLT-16N

## Application

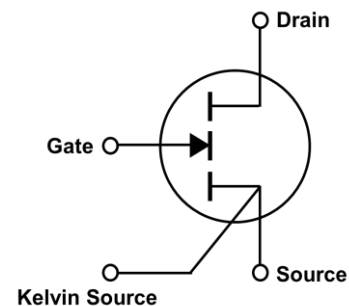
- High Switching Frequency Converter
- High Density Converter



## Key Performance Parameters

| Symbol           | Values | Unit |
|------------------|--------|------|
| $V_{DS,max}$     | 650    | V    |
| $I_D$            | 57.5   | A    |
| $I_{D,pulse}$    | 115    | A    |
| $R_{DS(on),typ}$ | 28     | mΩ   |
| $Q_g$            | 10.0   | nC   |
| $Q_{oss} @ 400V$ | 102    | nC   |
| $Q_{rr}$         | 0      | nC   |

|               |                   |
|---------------|-------------------|
| Gate          | 9                 |
| Kelvin Source | 10                |
| Drain         | 1,2,3,4,5,6,7,8   |
| Source        | 11,12,13,14,15,16 |



## Ordering Information

| Ordering Code | Package  | Ordering Unit (pcs) | Marking   |
|---------------|----------|---------------------|-----------|
| GNP3028TF-ZTR | TOLT-16N | 2,000               | GNP3028TF |

## Maximum Ratings

| Parameter                                       | Symbol              | Values      | Unit             | Conditions                |
|---|---------------------|-------------|------------------|---------------------------|
| Drain to Source Voltage, continuous             | $V_{DSS}$           | 650         | V                | -                         |
| Transient Drain to Source Voltage <sup>*1</sup> | $V_{DS(transient)}$ | 800         | V                | -                         |
| Gate to Source Voltage                          | $V_{GSS}$           | -10 to +7   | V                | -                         |
| Transient Gate to Source Voltage <sup>*2</sup>  | $V_{GS(transient)}$ | 8.5         | V                | -                         |
| Continuous Drain Current <sup>*3</sup>          | $I_D$               | 57.5        | A                | $T_c = 25^\circ\text{C}$  |
|   |                     | 28.5        |                  | $T_c = 125^\circ\text{C}$ |
| Pulse Drain Current <sup>*3*4</sup>             | $I_{D,pulse}$       | 115         | A                | $T_c = 25^\circ\text{C}$  |
|   |                     | 57.5        |                  | $T_c = 125^\circ\text{C}$ |
| Power Dissipation                               | $P_{tot}$           | 275         | W                | $T_c = 25^\circ\text{C}$  |
| Operation Temperature                           | $T_j$               | -55 to +150 | $^\circ\text{C}$ | -                         |
| Range of Storage Temperature                    | $T_{stg}$           | -55 to +150 | $^\circ\text{C}$ | -                         |

\*1  $t_{pulse}=1\mu\text{s}$ , <10 hrs of total time.

\*2  $t_{pulse}<20\text{ns}$ , <0.5 hrs of total time.

\*3 Limited and calculated by maximum temperature allowed.

\*4  $V_{GS}=6\text{V}$ , Duty=0.1,  $t_{pulse}=1\mu\text{s}$ .

Please note especially when using driver source that  $V_{GSS\_surge}$  must be in the range of absolute maximum rating.

## Thermal Resistance

| Parameter                               | Symbol       | Values |      |      | Unit               | Conditions  |
|---|--------------|--------|------|------|--------------------|---|
|   |              | Min    | Typ  | Max  |                    |   |
| Thermal Resistance, Junction to Ambient | $R_{thJA}$   | -      | -    | 34.0 | $^\circ\text{C/W}$ | Device on JEDEC Standard Board for Thermal Resistance |
| Thermal Resistance, Junction to Case    | $R_{thJC}$   | -      | 0.32 | 0.45 | $^\circ\text{C/W}$ | -   |
| Reflow Soldering Temperature            | $T_{solder}$ | -      | -    | 260  | $^\circ\text{C}$   | MSL 3   |

**Static Characteristics** ( $T_a = 25^\circ\text{C}$ )

| Parameter                                     | Symbol        | Values |      |     | Unit          | Conditions  |
|---|---------------|--------|------|-----|---------------|---|
|   |               | Min    | Typ  | Max |               |   |
| Gate Threshold Voltage                        | $V_{GS(th)}$  | 1.0    | 1.5  | 2.5 | V             | $V_{DS} = 30\text{mV}$ , $I_D = 46\text{mA}$                                |
| Drain to Source Breakdown Voltage             | $V_{(BR)DSS}$ | 650    | -    | -   | V             | $V_{GS} = 0\text{V}$ , $T_j = 25^\circ\text{C}$                             |
| Zero Gate Voltage Drain Current               | $I_{DSS}$     | -      | 0.7  | 70  | $\mu\text{A}$ | $V_{GS} = 0\text{V}$<br>$V_{DS} = 650\text{V}$<br>$T_j = 25^\circ\text{C}$  |
|   |               | -      | 14   | -   |               | $V_{GS} = 0\text{V}$<br>$V_{DS} = 650\text{V}$<br>$T_j = 150^\circ\text{C}$ |
| Gate to Source Leakage Current                | $I_{GSS+}$    | -      | 0.4  | 4.0 | mA            | $V_{GS} = 6.5\text{V}$ , $V_{DS} = 0\text{V}$                               |
| Static Drain to Source<br>On State Resistance | $R_{DS(on)}$  | -      | 30   | 39  | m $\Omega$    | $V_{GS} = 5.0\text{V}$<br>$I_D = 12\text{A}$<br>$T_j = 25^\circ\text{C}$    |
|   |               | -      | 62   | -   |               | $V_{GS} = 5.0\text{V}$<br>$I_D = 12\text{A}$<br>$T_j = 150^\circ\text{C}$   |
|   |               | -      | 28   | 36  |               | $V_{GS} = 6.0\text{V}$<br>$I_D = 12\text{A}$<br>$T_j = 25^\circ\text{C}$    |
|   |               | -      | 59   | -   |               | $V_{GS} = 6.0\text{V}$<br>$I_D = 12\text{A}$<br>$T_j = 150^\circ\text{C}$   |
| Gate Input Resistance                         | $R_G$         | -      | 0.15 | -   | $\Omega$      | $f = 100\text{MHz}$ , open drain  |

**Dynamic Characteristics** ( $T_a = 25^\circ\text{C}$ )

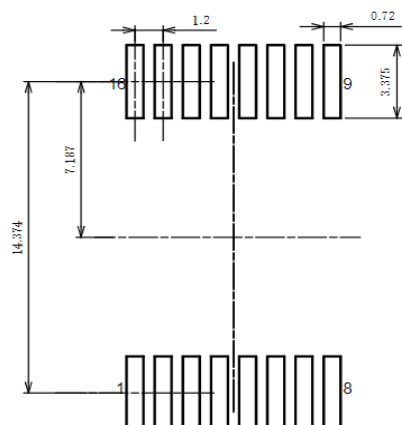
| Parameter                                    | Symbol       | Values |      |     | Unit | Conditions                                   |
|--|--------------|--------|------|-----|------|--|
|  |              | Min    | Typ  | Max |      |  |
| Input Capacitance                            | $C_{iss}$    | -      | 253  | -   | pF   | $V_{GS} = 0V$                                |
| Output Capacitance                           | $C_{oss}$    | -      | 137  | -   |      | $V_{DS} = 400V$                              |
| Reverse Transfer Capacitance                 | $C_{rss}$    | -      | 2.5  | -   |      | $f = 1\text{MHz}$                            |
| Effective Output Capacitance, Energy Related | $C_{o(er)}$  | -      | 195  | -   | pF   | $V_{GS} = 0V, V_{DS} = 0V \text{ to } 400V$  |
| Effective Output Capacitance, Time Related   | $C_{o(tr)}$  | -      | 255  | -   |      | $V_{GS} = 0V, V_{DS} = 0V \text{ to } 400V$  |
| Output Charge                                | $Q_{oss}$    | -      | 102  | -   | nC   | $V_{GS} = 0V, V_{DS} = 0V \text{ to } 400V$  |
| Turn - On Delay Time                         | $t_{d(on)}$  | -      | 13.5 | -   | ns   | $V_{DS} = 400V$                              |
| Rise Time                                    | $t_r$        | -      | 8.2  | -   |      | $I_D = 8A$                                   |
| Turn - Off Delay Time                        | $t_{d(off)}$ | -      | 40.1 | -   |      | $V_{GS} = 6V/0V$                             |
| Fall Time                                    | $t_f$        | -      | 26.2 | -   |      | $R_{on} = 10\Omega \quad R_{off} = 10\Omega$ |
| Total Gate Charge                            | $Q_g$        | -      | 10.0 | -   | nC   | $V_{DS} = 400V$                              |
| Gate to Source Charge                        | $Q_{gs}$     | -      | 0.5  | -   |      | $I_D = 8A$                                   |
| Gate to Drain Charge                         | $Q_{gd}$     | -      | 3.2  | -   |      | $V_{GS} = 6V/0V$                             |
| Gate Plateau Voltage                         | $V_{plat}$   | -      | 2.1  | -   | V    |  |

**Reverse Conduction Electrical Characteristics** ( $T_a = 25^\circ\text{C}$ )

| Parameter                       | Symbol    | Values |     |     | Unit | Conditions                  |
|---------------------------------|-----------|--------|-----|-----|------|-----------------------------|
|                                 |           | Min    | Typ | Max |      |                             |
| Source to Drain Reverse Voltage | $V_{SD}$  | -      | 2.5 | -   | V    | $V_{GS} = 0V, I_{SD} = 12A$ |
| Reverse Recovery Time           | $t_{rr}$  | -      | 0   | -   | ns   |                             |
| Reverse Recovery Charge         | $Q_{rr}$  | -      | 0   | -   | nC   |                             |
| Peak Reverse Recovery Current   | $I_{rrm}$ | -      | 0   | -   | A    |                             |

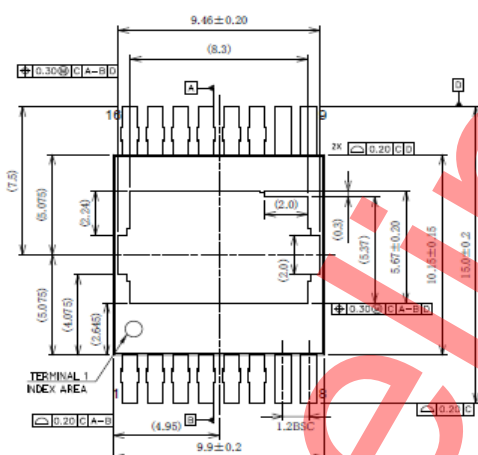
## Recommended Footprint

(mm)

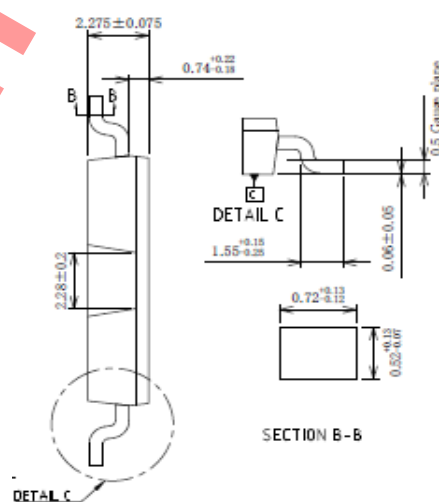


## Physical Dimension

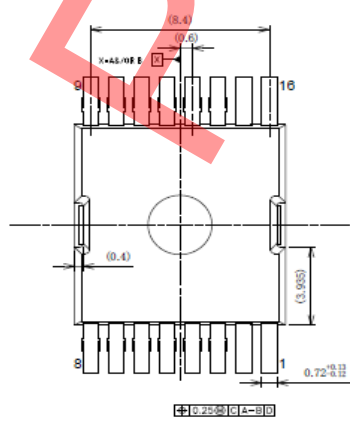
(mm)



(mm)



(mm)



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| JAPAN     | USA       | EU         | CHINA     |
|-----------|-----------|------------|-----------|
| CLASS III | CLASS III | CLASS II b | CLASS III |
| CLASS IV  |           | CLASS III  |           |

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  - Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - Sealing or coating our Products with resin or other coating materials
  - Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.) ; or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

## Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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## Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

## Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

## Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

## Precaution for Disposition

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